Symposium seeks a limited number of high impact late news papers relating to conference theme "Inflections for a Smart Society" with 24 March deadline…

Late News Call for Papers Issued by 2016 Symposium on VLSI Technology

HONOLULU, HAWAII – March 1, 2016 – A Call for Late News Papers has been issued for the 2016 Symposium on VLSI Technology, scheduled for the Hilton Hawaiian Village from June 13-16, 2016 (Technology). The deadline for late-news paper submission to the Symposium is March 24, 2016.

Accepted late news papers will be published as submitted, with no revisions permitted. Complete details for late-news paper submission can be found online at: http://vlsisymposium.org/authors-3/

Although the conference is held in conjunction with the Symposium on VLSI Circuits (June 15 – 17, 2016) at the same location, there is no corresponding late-news submission for the Symposium on VLSI Circuits.

For its limited number of late-news papers, the **Symposium on VLSI Technology** seeks those with emphasis on technical innovation, importance for the advancement of the field, originality and impact. Topics may include all aspects of IC technology, as well as the emerging IoT (Internet of Things) field, including:

- ***IoT systems & technologies***, including ultra-low power, heterogeneous integration, sensors, connectivity, power management, digital/analog, microcontrollers and application processors
- ***Stand-alone & embedded memories***, including DRAM, SRAM, non-volatile and emerging memory technologies
- ***CMOS Technology, microprocessors & SoCs***, including scaling, VLSI manufacturing concepts and yield optimization
- ***RF / analog /digital technologies*** for mixed-signal SoC, RF front end; analog, mixed-signal I/O, high voltage, imaging, MEMS, integrated sensors
- ***Process & material technologies,*** including advanced transistor process and architecture, modeling and reliability; alternate channel; advanced lithography, high-density patterning; SOI and III-V technologies, photonics, local interconnects and Cu/optical interconnect scaling
- ***Packaging technologies & System-in-Package (SiP)***
- ***Photonics Technology & 'Beyond CMOS' devices***

Joint Technology and Circuits focus sessions feature invited and contributed papers highlighting innovations and advances in materials, processes, devices, integration, reliability and modeling in the areas of advanced memories, 3D integration, and the impact of technology scaling on advanced circuit design. Submissions are strongly encouraged in the following areas of joint interest:

- *Design in scaled technologies:* scaling of digital, memory, analog and mixed-signal circuits in advanced CMOS processes
- *Design enablement***:** design for manufacturing, process/design co-optimization, on-die monitoring of variability and reliability
- *Embedded memory technology & design***:** SRAM, DRAM, Flash, PCRAM, RRAM, MRAM and NVRAM memory technologies
- *3D & heterogeneous integration***:** power and thermal management; inter-chip communications, SIP architectures and systems

Sponsoring Organizations
The Symposium on VLSI Technology is sponsored by the IEEE Electron Devices Society and the Japan Society of Applied Physics, in cooperation with the IEEE Solid State Circuits Society.

Further Information, Registration and Official Call for Papers
Visit: http://www.vlsisymposium.org.

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